

April 15, 2004

To: Commissioner of Patents and Trademarks  
Washington, D.C. 20231

Fr: George O. Saile      Reg. No. 19,572  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

Subject:

**Divisional Patent Application of**  
Serial No.: 10/315,534 12/10/02  
**ROMEO EMMANUEL P. ALVAREZ**  
**METHOD FOR FORMING A WAFER LEVEL CHIP**  
**SCALE PACKAGE, AND PACKAGE FORMED THEREBY**

**PRELIMINARY AMENDMENT**

Dear Sir:

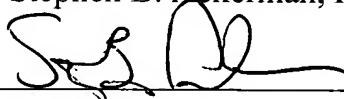
This is a preliminary amendment for the above referenced Divisional Patent  
Application. Please amend the above identified application for patent as follows:

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States  
Postal Service as first class mail in an envelope addressed to: Commissioner of Patents  
and Trademarks, Washington, D.C. 20231, on April 16, 2004.

Stephen B. Ackerman, Reg. No. 37,761

Signature/Date



4/16/04